

**REMARKS**

The Examiner is thanked for the thorough examination of the present application. The Office Action, however, tentatively rejected all claims. In response, claim 1 is amended and claims 11-20 are newly added. Support for the claim amendment and new claims, annotated above, is provided in the specification. Accordingly, no new matter has been added to the application by this amendment.

**Rejection under 35 USC 102**

The Office Action rejected claims 1, 4, 5, 6, 9 and 10 under 35USC 112(e) as allegedly anticipated by Shibasaki (6556439). For at least the following reasons, Applicant disagrees and requests that the rejection be withdrawn.

As amended, claim 1 recites:

1. An electronic device, comprising:  
a display unit; and

a host electrically connected to the display unit, comprising a module structure having a first substrate, at least one process unit, at least one heat-dissipating device and at least one second substrate, wherein the process unit is disposed on the first substrate, *the heat-dissipating device is disposed on the first substrate relative to the process unit*, the second substrate is disposed on the first substrate relative to the process unit, and the second substrate and the first substrate have the same structure and texture.

(*Emphasis added*). Applicant respectfully submits that claim 1 defines over the cited art for at least the reason that the cited art fails to disclose at least those features emphasized above.

In Shibasaki's Fig. 3, the heat conductive sheet (37) ("second substrate" referenced by the Office Action) is disposed between the heat conductive case (35) and the IC chip (11) of the semiconductor package (9). No contact is made or formed between the heat conductive sheet (37) and the circuit board (8) ("first substrate" referenced by the Office Action).

In Fig. 2B of the present application, the process unit (2) is disposed on the first substrate (1) and the second substrate (4) is disposed on the first substrate (1) relative to the process unit (2). The heat-dissipating device (3) is disposed on the first substrate (1) relative to the process unit (2), and the second substrate (4) connected to the first substrate (1), for example, screws (411), contacts the first substrate (1). This structure is embodied in features of claim 1.

For at least these reasons, the structure of the electronic device and the module structure defined in claim 1 patently define over the teaching of Shibasaki. For at least the same reasons dependent claims 2-10 patently define over the cited art.

Likewise, independent claims 11 and 16 embody features that patently define over Shibasaki. Therefore the newly added claims 11-20 patently define over the cited art.

#### Rejection under 35 USC 103

The Office Action rejected claims 2, 3, 7 and 8 under 35 U.S.C. 103(a) as allegedly unpatentable over Shibasaki (6,556,439).

In the present application, the second substrate (4) and the first substrate (1) have the same structure and texture, i.e., the first and second substrates (1 and 4) are formed from the same material (the second substrate (4) is made from the first substrate), so that the second substrate (4) with multi-layer structure can reinforce the first substrate (1).

In Shibasaki's description and figures, it is clear that the heat conductive sheet (37) is used for conducting heat from the IC chip (11) of the semiconductor package (9). Shibasaki does not teach that the heat conductive sheet (37) can be connected to or contact the circuit board (8), or imply that the material and structure of the heat conductive sheet (37) is the same as the circuit

board (8).

For at least these additional reasons, claims 2, 3, 7, and 8 patently define over the cited art.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

No fee is believed to be due in connection with this amendment and response to Office Action. If, however, any fee is believed to be due, you are hereby authorized to charge any such fee to deposit account No. 20-0778.

Respectfully submitted,

By:

  
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